

Title (en)

METHOD FOR EXPOSING AN ELECTRICAL CONTACT

Title (de)

VERFAHREN ZUM FREILEGEN EINES ELEKTRISCHEN KONTAKTS

Title (fr)

PROCÉDÉ DE DÉNUDATION D'UN CONTACT ÉLECTRIQUE

Publication

**EP 2449602 A2 20120509 (DE)**

Application

**EP 10726125 A 20100629**

Priority

- EP 2010059167 W 20100629
- DE 102009026064 A 20090629
- DE 102009044022 A 20090916

Abstract (en)

[origin: WO2011000814A2] The invention relates to a method for exposing at least one electrical contact, which is covered by at least one layer made of plastic, by means of a laser beam. In order to allow the targeted and reproducible exposing of the electrical contact in an automated process, the location of the at least one electrical contact is determined by means of a sensor, and the at least one layer made of plastic is removed in a flat area, in consideration of the determined location of the electrical contact and according to a pattern stored in a controller of a laser scanner, the projection of said flat area being inside of the contact in the direction of the contact.

IPC 8 full level

**H01L 31/18** (2006.01)

CPC (source: EP US)

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Citation (search report)

See references of WO 2011000814A2

Citation (examination)

- JP H10335687 A 19981218 - TOSHIBA CORP
- WO 03061013 A1 20030724 - BP CORP NORTH AMERICA INC [US]
- DE 102007011749 A1 20080313 - INST SOLARENERGIEFORSCHUNG [DE]

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